

# CM1420, CM1422

## LCD EMI Filter Array with ESD Protection

### Description

The CM1420 and CM1422 are EMI filter arrays with ESD protection, which integrate six and eight Pi-filters (C-R-C), respectively. The CM1420/22 has component values of 15 pF – 100  $\Omega$  – 15 pF. These devices include ESD protection diodes on every pin, which provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The ESD diodes connected to the filter ports safely dissipate ESD strikes of  $\pm 15$  kV, well beyond the maximum requirement of the IEC 61000-4-2 international standard. Using the MIL-STD-883 (Method 3015) specification for Human Body Model (HBM) ESD, the pins are protected for contact discharges at greater than  $\pm 30$  kV.

This device is particularly well suited for portable electronics (e.g. wireless handsets, PDAs, notebook computers) because of its small package format and easy-to-use pin assignments. In particular, the CM1420/22 is ideal for EMI filtering and protecting data lines from ESD for the LCD display in clamshell handsets.

The CM1420 and CM1422 incorporate *OptiGuard*<sup>™</sup> coating which results in improved reliability at assembly. The CM1420 and CM1422 are available in space-saving, low-profile chip scale packages with RoHS compliant lead-free finishing.

### Features

- Functionally and Pin Compatible with CSPEMI606 (CM1420) and CSPEMI608 (CM1422) Devices
- *OptiGuard*<sup>™</sup> Coated for Improved Reliability at Assembly
- Six and Eight Channels of EMI Filtering
- $\pm 15$  kV ESD Protection on Each Channel (IEC 61000-4-2 Level 4, Contact Discharge)
- $\pm 30$  kV ESD Protection on Each Channel (HBM)
- Better than 30 dB of Attenuation at 1 GHz to 3 GHz
- Chip Scale Package Features Extremely Low Lead Inductance for Optimum Filter and ESD Performance
- 15-Bump, 2.960 mm x 1.330 mm Footprint Chip Scale Package (CM1420)
- 20-Bump, 4.000 mm x 1.458 mm Footprint Chip Scale Package (CM1422)
- These Devices are Pb-Free and are RoHS Compliant

### Applications

- LCD Data Lines in Clamshell Wireless Handsets
- EMI Filtering & ESD Protection for High-Speed I/O Data Ports
- Wireless Handsets / Cell Phones
- Notebook Computers
- PDAs / Handheld PCs
- EMI Filtering for High-Speed Data Lines



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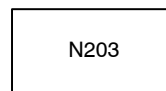


**WLCSP15  
CP SUFFIX  
CASE 567BS**

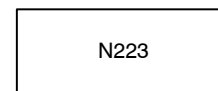


**WLCSP20  
CP SUFFIX  
CASE 567BZ**

### MARKING DIAGRAM



CM1420  
15-Bump CSP Package



CM1422  
20-Bump CSP Package

N203 = CM1420-03CP  
N223 = CM1422-03CP

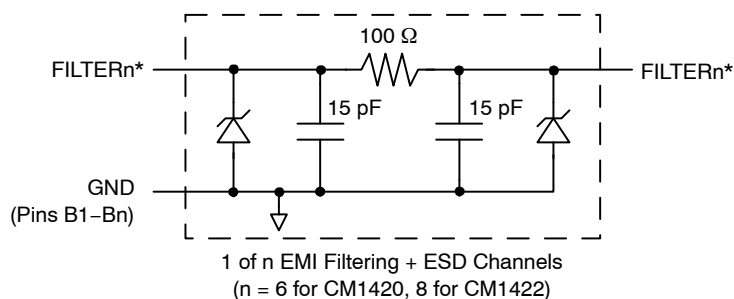
### ORDERING INFORMATION

| Device      | Package             | Shipping <sup>†</sup> |
|-------------|---------------------|-----------------------|
| CM1420-03CP | CSP-15<br>(Pb-Free) | 3500/Tape & Reel      |
| CM1422-03CP | CSP-20<br>(Pb-Free) | 3500/Tape & Reel      |

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

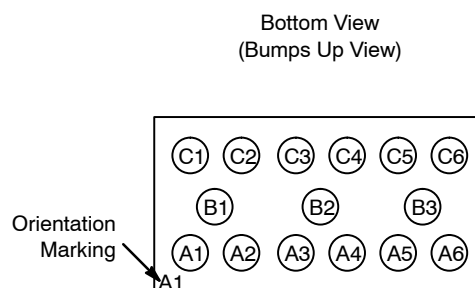
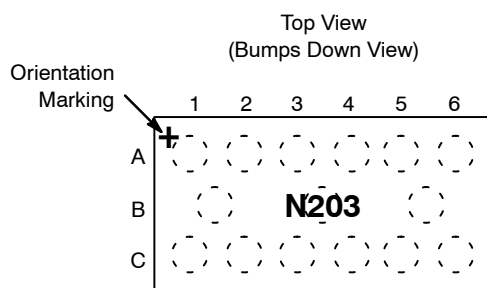
# CM1420, CM1422

## BLOCK DIAGRAM

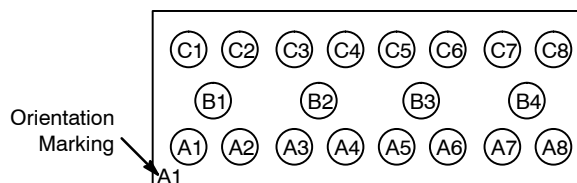
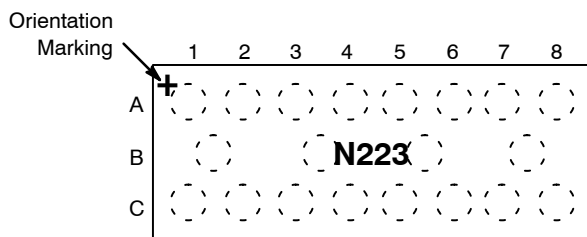


\*See Package/Pinout Diagrams for expanded pin information.

## PACKAGE / PINOUT DIAGRAMS



CM1420 CSP Package



CM1422 CSP Package

Table 1. PIN DESCRIPTIONS

| CM1420 | CM1422 | Name    | Description      | CM1420 | CM1422 | Name    | Description      |
|--------|--------|---------|------------------|--------|--------|---------|------------------|
| Pin(s) | Pin(s) |         |                  | Pin(s) | Pin(s) |         |                  |
| A1     | A1     | FILTER1 | Filter Channel 1 | C1     | C1     | FILTER1 | Filter Channel 1 |
| A2     | A2     | FILTER2 | Filter Channel 2 | C2     | C2     | FILTER2 | Filter Channel 2 |
| A3     | A3     | FILTER3 | Filter Channel 3 | C3     | C3     | FILTER3 | Filter Channel 3 |
| A4     | A4     | FILTER4 | Filter Channel 4 | C4     | C4     | FILTER4 | Filter Channel 4 |
| A5     | A5     | FILTER5 | Filter Channel 5 | C5     | C5     | FILTER5 | Filter Channel 5 |
| A6     | A6     | FILTER6 | Filter Channel 6 | C6     | C6     | FILTER6 | Filter Channel 6 |
| –      | A7     | FILTER7 | Filter Channel 7 | –      | C7     | FILTER7 | Filter Channel 7 |
| –      | A8     | FILTER8 | Filter Channel 8 | –      | C8     | FILTER8 | Filter Channel 8 |
| B1–B3  | B1–B4  | GND     | Device Ground    |        |        |         |                  |

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## SPECIFICATIONS

**Table 2. ABSOLUTE MAXIMUM RATINGS**

| Parameter                 | Rating      | Units |
|---------------------------|-------------|-------|
| Storage Temperature Range | -65 to +150 | °C    |
| DC Power per Resistor     | 100         | mW    |
| DC Package Power Rating   | 500         | mW    |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

**Table 3. STANDARD OPERATING CONDITIONS**

| Parameter                   | Rating     | Units |
|-----------------------------|------------|-------|
| Operating Temperature Range | -40 to +85 | °C    |

**Table 4. ELECTRICAL OPERATING CHARACTERISTICS** (Note 1)

| Symbol             | Parameter                                                                                                                          | Conditions                            | Min                  | Typ          | Max         | Units    |
|--------------------|------------------------------------------------------------------------------------------------------------------------------------|---------------------------------------|----------------------|--------------|-------------|----------|
| R                  | Resistance                                                                                                                         |                                       | 80                   | 100          | 120         | $\Omega$ |
| C                  | Capacitance                                                                                                                        | At 2.5 V DC, 1 MHz,<br>30 mV AC       | 12                   | 15           | 18          | pF       |
| V <sub>DIODE</sub> | Diode Standoff Voltage                                                                                                             | I <sub>DIODE</sub> = 10 $\mu$ A       |                      | 6.0          |             | V        |
| I <sub>LEAK</sub>  | Diode Leakage Current (reverse bias)                                                                                               | V <sub>DIODE</sub> = 3.3 V            |                      | 100          | 200         | nA       |
| V <sub>SIG</sub>   | Signal Clamp Voltage<br>Positive Clamp<br>Negative Clamp                                                                           | I <sub>LOAD</sub> = 10 mA<br>(Note 3) | 5.6<br>-1.5          | 6.8<br>-0.8  | 9.0<br>-0.4 | V        |
| V <sub>ESD</sub>   | In-system ESD Withstand Voltage<br>a) Human Body Model, MIL-STD-883, Method 3015<br>b) Contact Discharge per IEC 61000-4-2 Level 4 | (Note 2)                              | $\pm$ 30<br>$\pm$ 15 |              |             | kV       |
| R <sub>DYN</sub>   | Dynamic Resistance<br>Positive<br>Negative                                                                                         |                                       |                      | 2.30<br>0.90 |             | $\Omega$ |
| f <sub>C</sub>     | Cut-off Frequency<br>Z <sub>SOURCE</sub> = 50 $\Omega$ , Z <sub>LOAD</sub> = 50 $\Omega$                                           | R = 100 $\Omega$ , C = 15 pF          |                      | 120          |             | MHz      |

1. T<sub>A</sub> = 25 °C unless otherwise specified.
2. ESD applied to input and output pins with respect to GND, one at a time.
3. Clamping voltage is measured at the opposite side of the EMI filter to the ESD pin. For example, if ESD is applied to Pin A1, then clamping voltage is measured at Pin C1.

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## PERFORMANCE INFORMATION

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

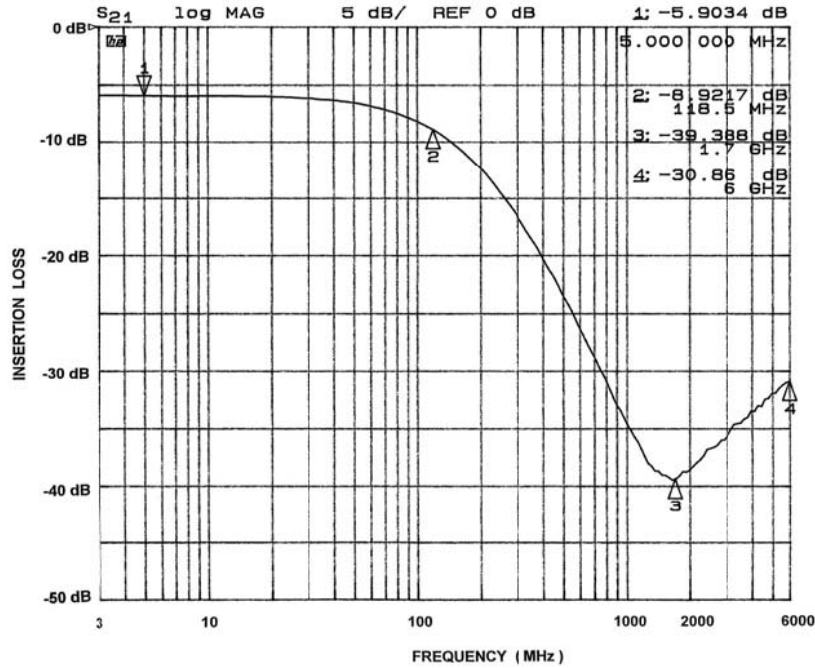


Figure 1. Insertion Loss vs. Frequency (A1-C1 to GND B1)

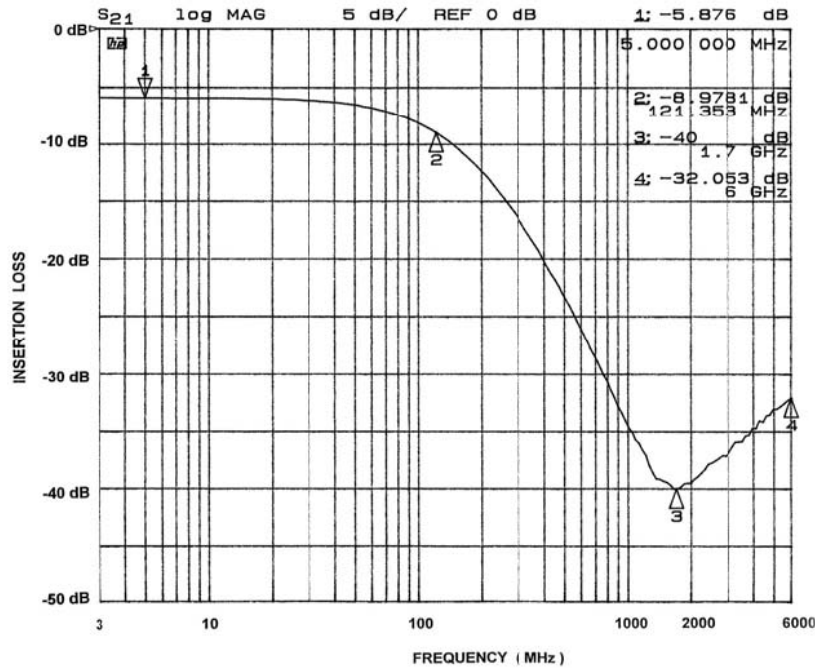


Figure 2. Insertion Loss vs. Frequency (A2-C2 to GND B1)

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## PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

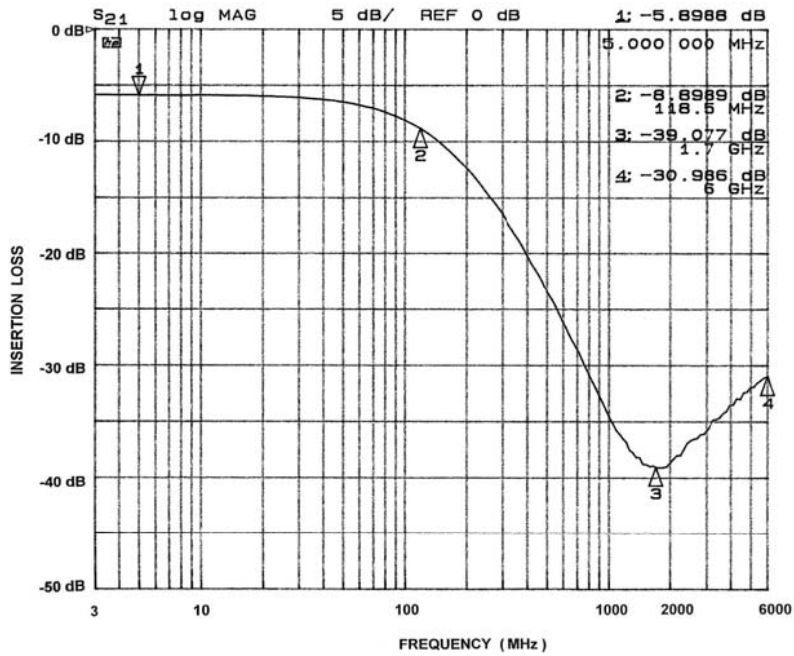


Figure 3. Insertion Loss vs. Frequency (A3-C3 to GND B2)

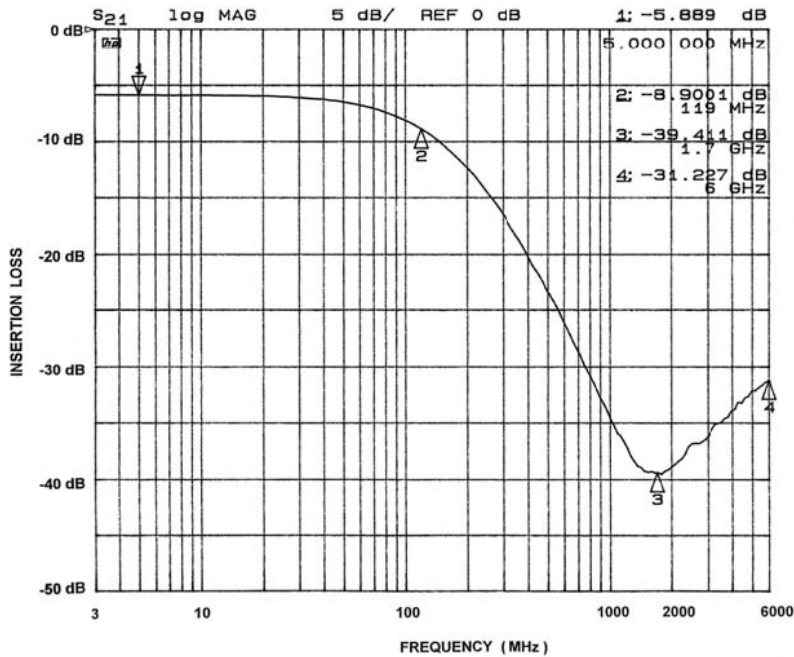


Figure 4. Insertion Loss vs. Frequency (A4-C4 to GND B2)

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## PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

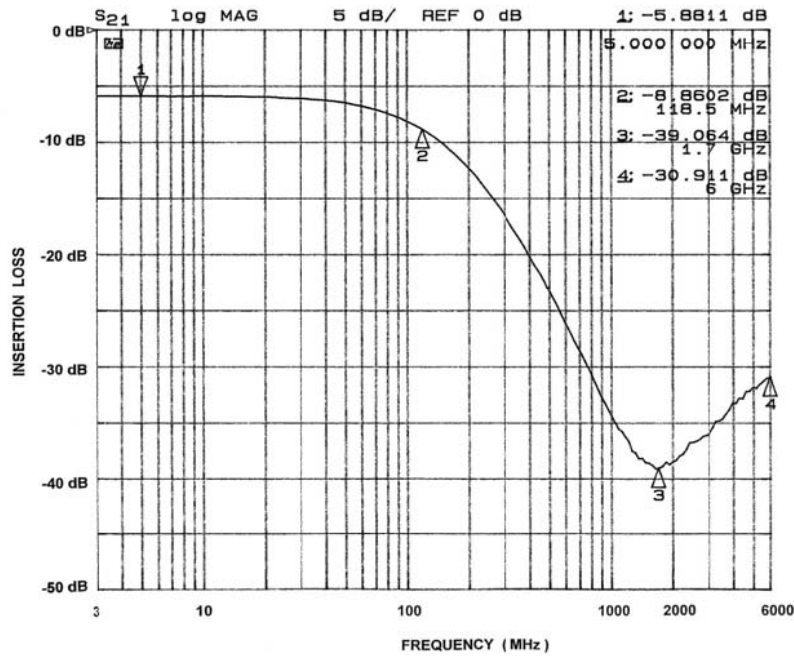


Figure 5. Insertion Loss vs. Frequency (A5-C5 to GND B3)

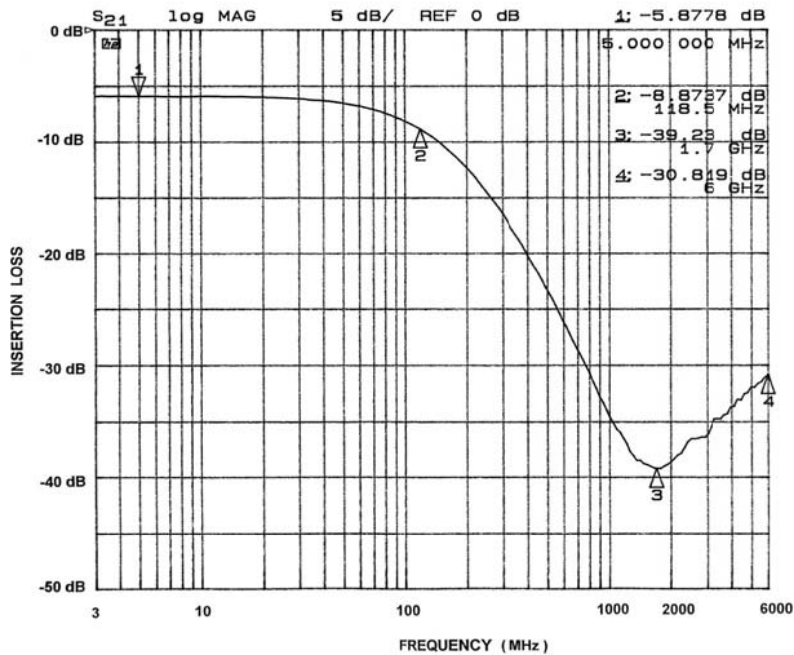


Figure 6. Insertion Loss vs. Frequency (A6-C6 to GND B3)

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## PERFORMANCE INFORMATION (Cont'd)

Typical Filter Performance ( $T_A = 25^\circ\text{C}$ , DC Bias = 0 V, 50  $\Omega$  Environment)

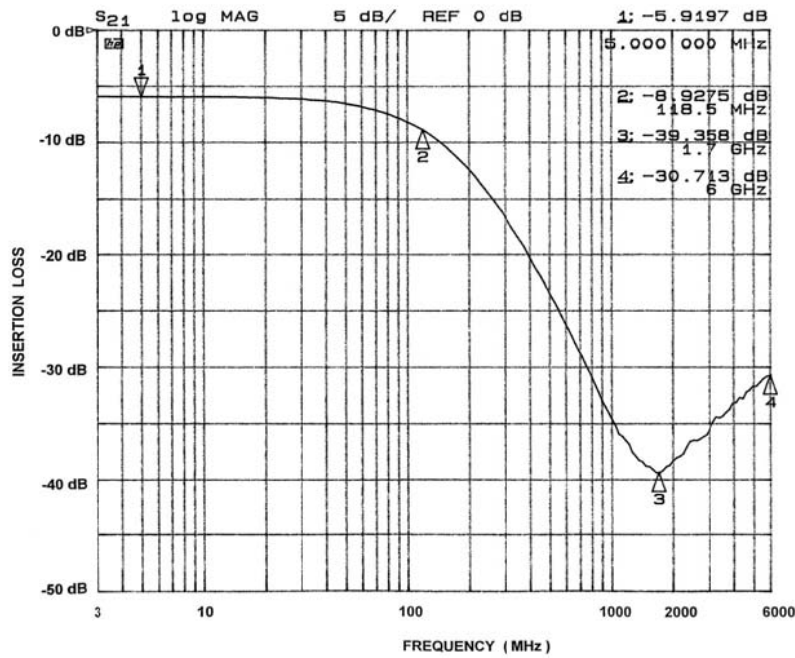


Figure 7. Insertion Loss vs. Frequency  
(A7-C7 to GND B4, CM1422 Only)

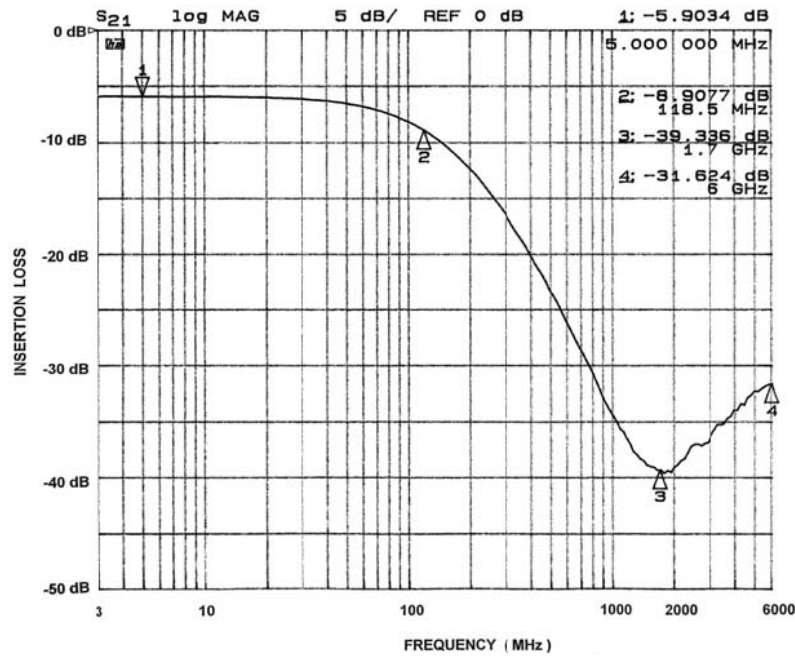
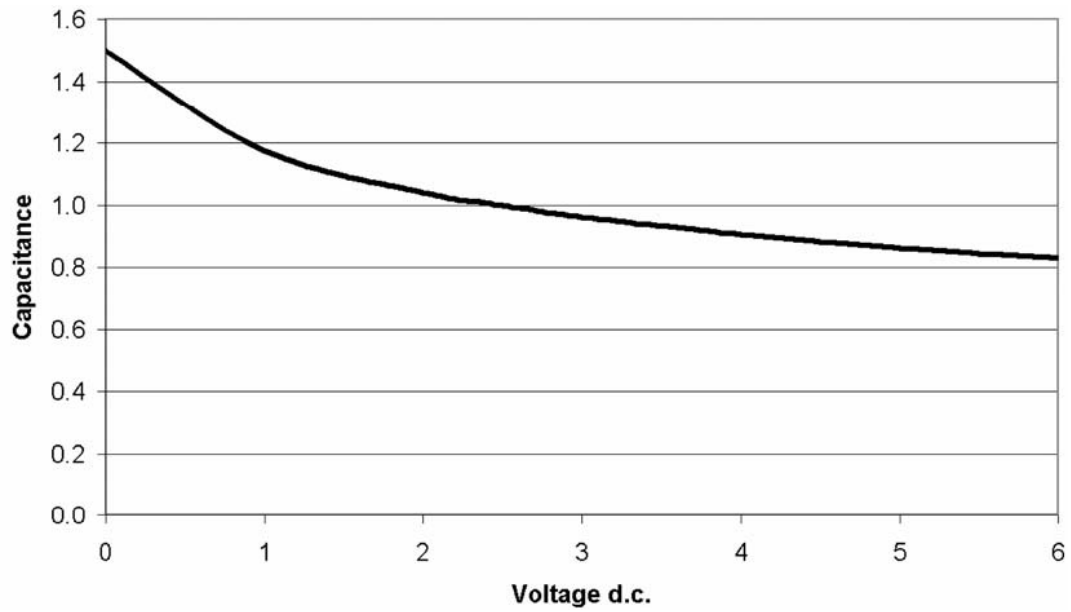


Figure 8. Insertion Loss vs. Frequency  
(A8-C8 to GND B4, CM1422 Only)

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### PERFORMANCE INFORMATION (Cont'd)



**Figure 9. Filter Capacitance vs. Input Voltage over Temperature  
(normalized to capacitance at 2.5 VDC and 25°C)**

APPLICATION INFORMATION

Table 5. PRINTED CIRCUIT BOARD RECOMMENDATIONS

| Parameter                                                                          | Value                        |
|------------------------------------------------------------------------------------|------------------------------|
| Pad Size on PCB                                                                    | 0.240 mm                     |
| Pad Shape                                                                          | Round                        |
| Pad Definition                                                                     | Non-Solder Mask defined pads |
| Solder Mask Opening                                                                | 0.290 mm Round               |
| Solder Stencil Thickness                                                           | 0.125 – 0.150 mm             |
| Solder Stencil Aperture Opening (laser cut, 5% tapered walls)                      | 0.300 mm Round               |
| Solder Flux Ratio                                                                  | 50/50 by volume              |
| Solder Paste Type                                                                  | No Clean                     |
| Pad Protective Finish                                                              | OSP (Entek Cu Plus 106A)     |
| Tolerance – Edge To Corner Ball                                                    | $\pm 50\ \mu\text{m}$        |
| Solder Ball Side Coplanarity                                                       | $\pm 20\ \mu\text{m}$        |
| Maximum Dwell Time Above Liquidous                                                 | 60 seconds                   |
| Maximum Soldering Temperature for Lead-free Devices using a Lead-free Solder Paste | 260°C                        |

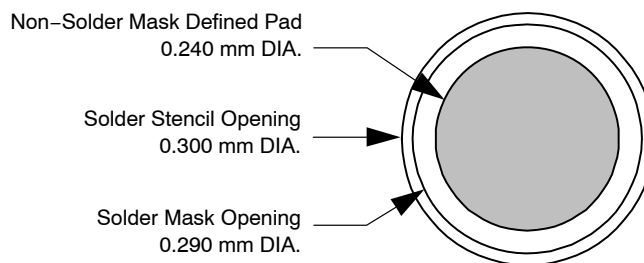


Figure 10. Recommended Non-Solder Mask Defined Pad Illustration

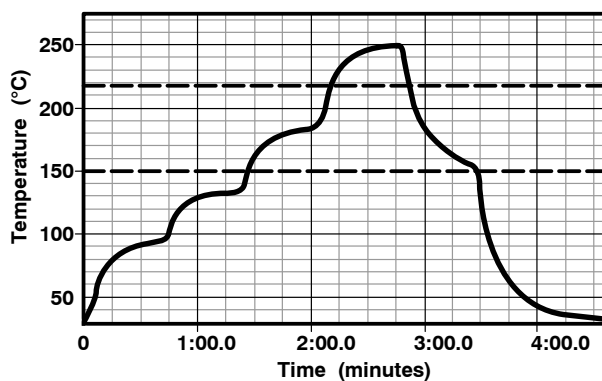


Figure 11. Lead-free (SnAgCu) Solder Ball Reflow Profile

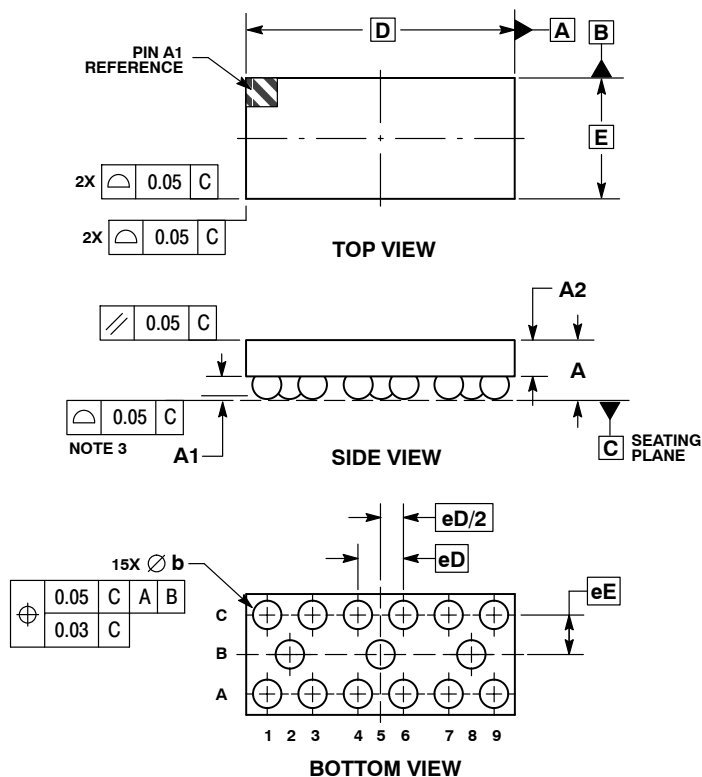
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## PACKAGE DIMENSIONS

WLCSP15, 2.96x1.33

CASE 567BS-01

ISSUE O

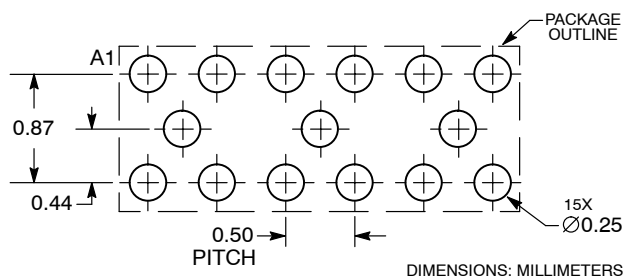


### NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

| DIM | MILLIMETERS |      |
|-----|-------------|------|
|     | MIN         | MAX  |
| A   | 0.56        | 0.65 |
| A1  | 0.21        | 0.27 |
| A2  | 0.40        | REF  |
| b   | 0.29        | 0.35 |
| D   | 2.96        | BSC  |
| E   | 1.33        | BSC  |
| eD  | 0.50        | BSC  |
| eE  | 0.435       | BSC  |

### RECOMMENDED SOLDERING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

